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# ZXGD3001E6

## 9A(peak) Gate driver in SOT23-6

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### General description

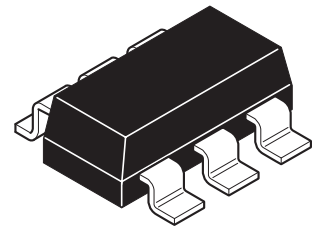
The ZXGD3001E6 is a high-speed non-inverting single MOSFET gate driver capable of driving up to 9A into a MOSFET or IGBT gate capacitive load from supply voltages up to 12V. With typical propagation delay times down to 3ns and rise/fall times down to 11ns this device ensures rapid switching of the power MOSFET or IGBT to minimize power losses and distortion in high current fast switching applications.

The ZXGD3001E6 is inherently rugged to latch-up and shoot-through, and its wide supply voltage range allows full enhancement to minimize on-losses of the power MOSFET or IGBT.

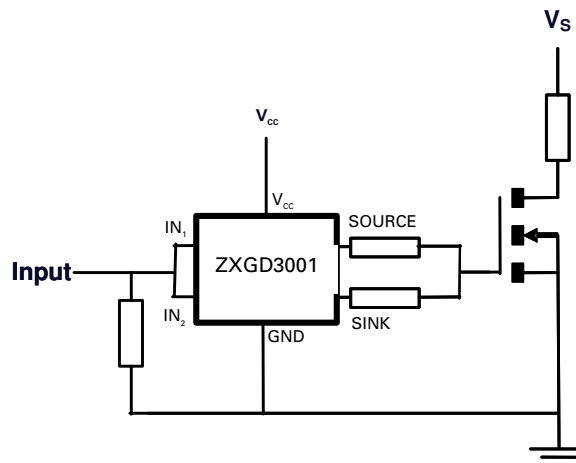
Its low input voltage requirement and high current gain allows high current driving from low voltage controller ICs, and the optimized pin-out SOT23-6 package with separate source and sink pins eases board layout, enabling reduced parasitic inductance and independent control of rise and fall slew rates.

### Features

- 12V operating voltage range
- 9 Amps peak output current
- Fast switching emitter-follower configuration
  - 3ns propagation delay time
  - 11ns rise/fall time, 1000pF load
- Low input current requirement
  - 4.2A(source)/2.2A(sink) output current from 10mA input
- SOT23-6 package
- Separate source and sink outputs for independent control of rise and fall time
- Optimized pin-out to ease board layout and minimize trace inductance
- No Latch Up
- No shoot through
- Near - Zero quiescent and output leakage current



### Typical application circuit



# ZXGD3001E6

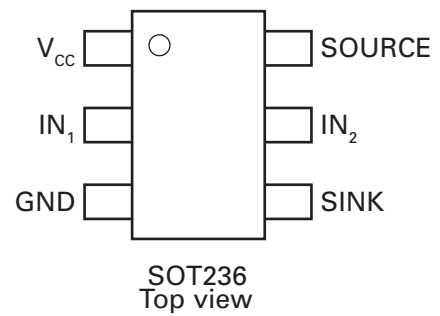
## Applications

Power MOSFET and IGBT Gate Driving in

- Synchronous switch-mode power supplies
- Secondary side synchronous rectification
- Plasma Display Panel power modules
- 1, 2 and 3-phase motor control circuits
- Audio switching amplifier power output stages

## Pin configuration

Pin Name	Pin Function
V <sub>CC</sub>	Driver supply
IN <sub>1</sub> / IN <sub>2</sub>	Driver input pins. These are normally connected together by circuit tracks.
GND	Ground
SOURCE	Source current output.
SINK	Sink current output.



## Ordering information

DEVICE	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXGD3001E6TA	7	8 embossed	3000

## Device marking

3001

# ZXGD3001E6

## Absolute maximum ratings

Parameter	Symbol	Limit	Unit
Supply voltage	$V_{CC}$	12	V
Input voltage	$V_{IN}$	12	V
Peak sink current <sup>(c)</sup>	$I_{(sink)PK}$	9	A
Source current @ $I_{IN1} + I_{IN2} = 10mA^{(a)}$	$I_{(source)}$	4.2	A
Sink current @ $I_{IN1} + I_{IN2} = 10mA^{(a)}$	$I_{(sink)}$	2.2	A
Input current <sup>(c)</sup>	$I_{IN1}, I_{IN2}$	1	A
Power dissipation at $T_A = 25^{\circ}C^{(a)(b)}$	$P_D$	1.1	W
Linear derating factor		8.8	mW/ $^{\circ}C$
Operating and storage temperature range	$T_j, T_{stg}$	-55 to +150	$^{\circ}C$

## Thermal resistance

Parameter	Symbol	Value	Unit
Junction to ambient <sup>(a)(b)</sup>	$R_{\theta JA}$	113	$^{\circ}C/W$

### NOTES:

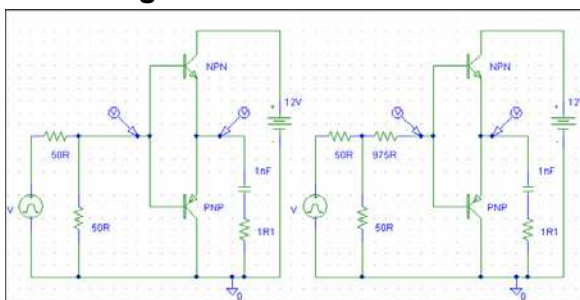
- (a) For a device surface mounted on 25mm x 25mm x 0.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- (b) For device with two active dice running at equal power.
- (c) Pulse width  $\leq 300\mu s$  limit repetition rate to comply with maximum junction temperature.

# ZXGD3001E6

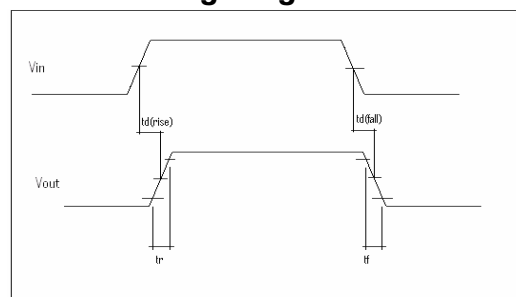
Electrical characteristics (at  $T_{amb} = 25^{\circ}\text{C}$  unless otherwise stated).

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Output voltage, high	$V_{OH}$		$V_{CC} - 0.4$		V	$I_{SOURCE} = 1\mu\text{A}$
Output voltage, low	$V_{OL}$		0.4		V	$I_{SINK} = 1\mu\text{A}$
Source output leakage current	$I_{L(source)}$			1	$\mu\text{A}$	$V_{CC} = 12\text{V}$ , $V_{IN1} = V_{IN2} = 0\text{V}$
Sink output leakage current	$I_{L(sink)}$			1	$\mu\text{A}$	$V_{CC} = 12\text{V}$ , $V_{IN1} = V_{IN2} = V_{CC}$
Quiescent current	$I_Q$			50	nA	$V_{CC} = 9.6\text{V}$ , $V_{IN1} = V_{IN2} = 0\text{V}$
Source output current	$I_{(source)}$	1	1.7		A	$I_{IN1} + I_{IN2} = 2.5\text{mA}$
Sink output current	$I_{(sink)}$	0.7	1.1		A	$I_{IN1} + I_{IN2} = 2.5\text{mA}$
Source output current	$I_{(source)}$	2.7	4.2		A	$I_{IN1} + I_{IN2} = 10\text{mA}$
Sink output current	$I_{(sink)}$	1.5	2.2		A	$I_{IN1} + I_{IN2} = 10\text{mA}$
Source output current	$I_{(source)PK}$		9		A	$I_{IN1} + I_{IN2} = 1\text{A}$
Sink output current	$I_{(sink)PK}$		9		A	$I_{IN1} + I_{IN2} = 1\text{A}$
Gate driver switching times	$t_{d(rise)}$ $t_r$ $t_{d(fall)}$ $t_f$		1.3 7.3 3 11		ns ns ns ns	$C_L = 1\text{nF}$ , $R_L = 1\Omega$ , $V_{CC} = 8\text{V}$ , $V_{IN} = 6\text{V}$ , $R_S = 25\Omega$
Gate driver switching times	$t_{d(rise)}$ $t_r$ $t_{d(fall)}$ $t_f$		9 141.5 14 151		ns ns ns ns	$C_L = 1\text{nF}$ , $R_L = 1\Omega$ , $V_{CC} = 8\text{V}$ , $V_{IN} = 6\text{V}$ , $R_S = 1\text{k}\Omega$

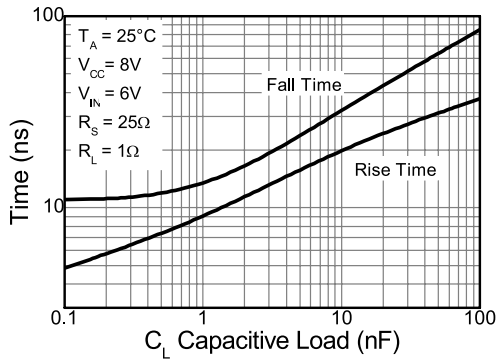
## Switching Time Test Circuits



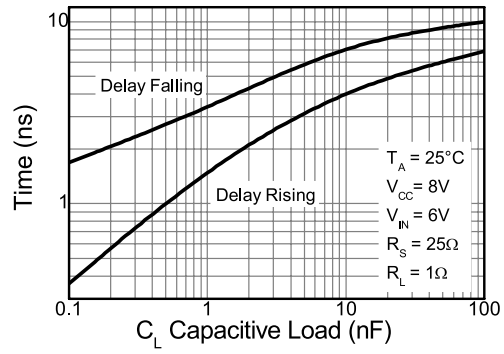
## Timing Diagram



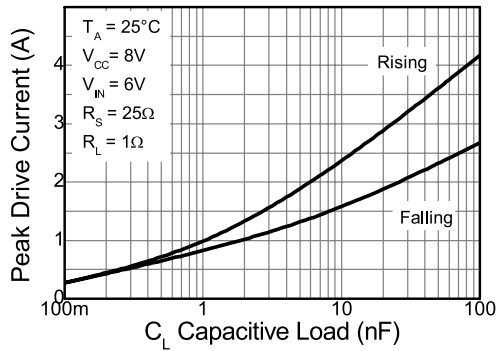
## Typical gate driver characteristics



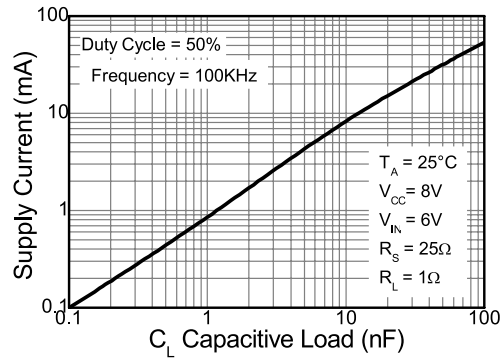
**Rise and Fall Time**



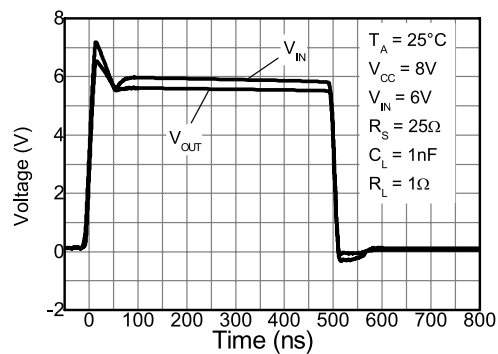
**Propagation Delay**



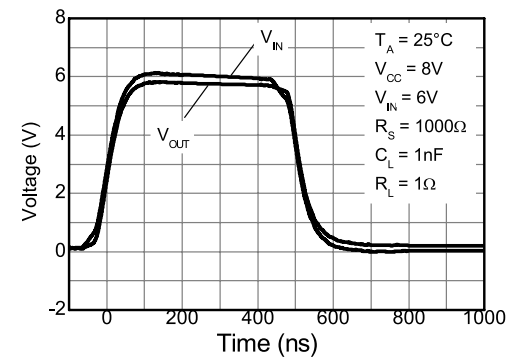
**Peak Drive Current**



**Supply Current**

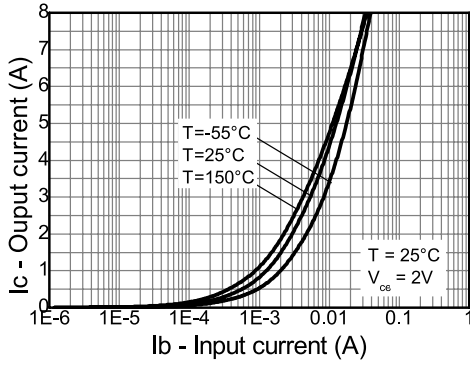


**Switching Speed**

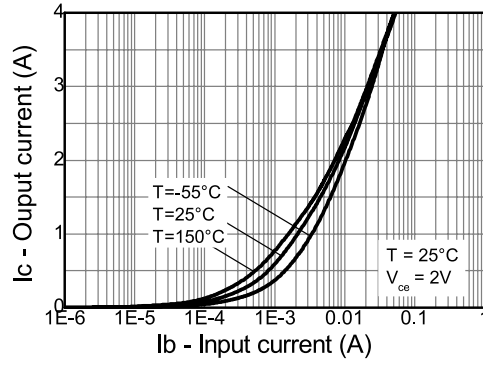


**Switching Speed**

# ZXGD3001E6



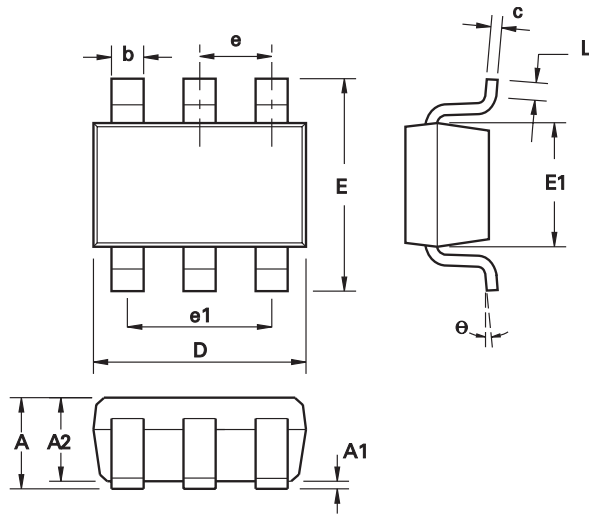
Source Current Vs Input Current



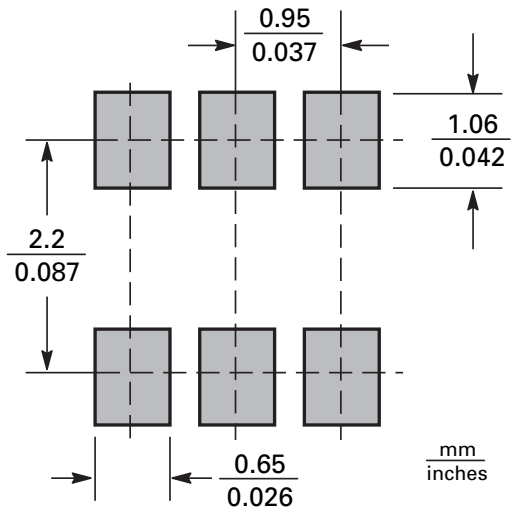
Sink Current Vs Input Current

# ZXGD3001E6

## SOT23-6 Package outline



## Pad layout details



DIM	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.45	0.0354	0.0570
A1	0.00	0.15	0.00	0.0059
A2	0.90	1.30	0.0354	0.0511
b	0.35	0.50	0.0078	0.0196
C	0.09	0.26	0.0035	0.0102
D	2.70	3.10	0.1062	0.1220
E	2.20	3.20	0.0866	0.1181
E1	1.30	1.80	0.0511	0.0708
L	0.10	0.60	0.0039	0.0236
e	0.95 REF		0.0374 REF	
e1	1.90 REF		0.0748 REF	
L	0°	30°	0°	30°

**Note:** Controlling dimensions are in millimeters. Approximate dimensions are provided in inches



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